Vincotech

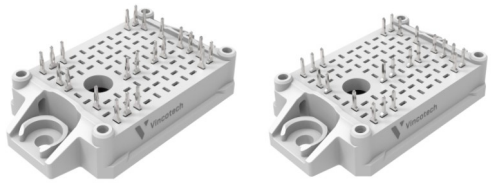
10-EZ126PA025M7-L858F78T
10-E1126PA025M7-L858F78Z
datasheet

***flow*PACK E1** **1200 V / 25 A**

Features

- IGBT M7 with low V_{CEsat} and improved EMC behavior
- Standard industrial housing
- Optimized $R_{th(j-s)}$ with Phase Change Material
- Built-in NTC

flow E1 12 mm housing

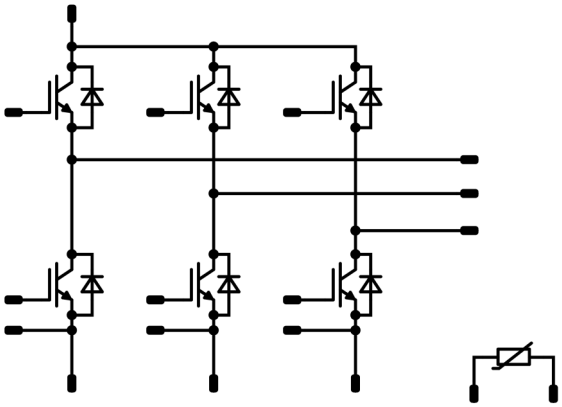


Press-fit pin Solder pin

Target applications

- Industrial Drives

Schematic



Types

- 10-EZ126PA025M7-L858F78T
- 10-E1126PA025M7-L858F78Z

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition		Value	Unit
Inverter Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current	I_C			25	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		50	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	96	W
Gate-emitter voltage	V_{GES}			±20	V
Maximum junction temperature	T_{jmax}			175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition		Value	Unit
Inverter Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Continuous (direct) forward current	I_F			25	A
Repetitive peak forward current	I_{FRM}	T_j limited by T_{jmax}		50	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	71	W
Maximum junction temperature	T_{jmax}			175	°C
Module Properties					
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	6000	V
		AC Voltage	t_p = 1 min	2500	V
Creepage distance				min. 12,7	mm
Clearance		with solder pins		8,62	mm
		with Press-fit pins		8,62	mm
Comparative Tracking Index	CTI			≥ 600	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,0025	25	5,4	6,0	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		25	25 125 150		1,65 1,89 1,95	2,15	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			70	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}		0	10		25		4800		pF
Output capacitance	C_{oes}							170		
Reverse transfer capacitance	C_{res}							57		
Gate charge	Q_g		15	600	25	25		180		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,99		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 16 Ω R_{goff} = 16 Ω	±15	600	25	25 125 150		147 149 145		ns
Rise time	t_r					25 125 150		29 33 34		
Turn-off delay time	$t_{d(off)}$					25 125 150		171 191 196		
Fall time	t_f					25 125 150		95 110 115		
Turn-on energy (per pulse)*	E_{on}	Q_{rFWD} = 2,5 µC Q_{rFWD} = 3,9 µC Q_{rFWD} = 4,3 µC				25 125 150		2,06 2,66 2,82		mWs
Turn-off energy (per pulse)*	E_{off}					25 125 150		1,67 2,18 2,29		

* Ls = 14 nH

Characteristic Values

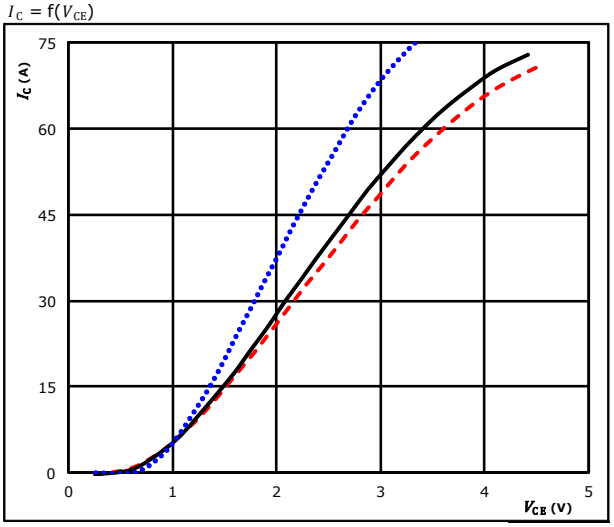
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				25	25 125 150		1,63 1,70 1,69	2,1	V
Reverse leakage current	I_R			1200		25			35	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,34		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 645 A/µs di/dt = 673 A/µs di/dt = 633 A/µs	±15	600	25	25 125 150		21 23 23		A
Reverse recovery time	t_{rr}					25 125 150		254 367 404		ns
Recovered charge	Q_r					25 125 150		2,54 3,88 4,28		µC
Reverse recovered energy	E_{rec}					25 125 150		0,884 1,45 1,61		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		217 134 132		A/µs
Thermistor										
Rated resistance	R					25		5		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 493 Ω				100	-5		+5	%
Power dissipation	P					25		245		mW
Power dissipation constant						25		1,4		mW/K
B-value	$B_{(25/50)}$	Tol. ±2 %				25		3375		K
B-value	$B_{(25/100)}$	Tol. ±2 %				25		3437		K
Vincotech NTC Reference									K	

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

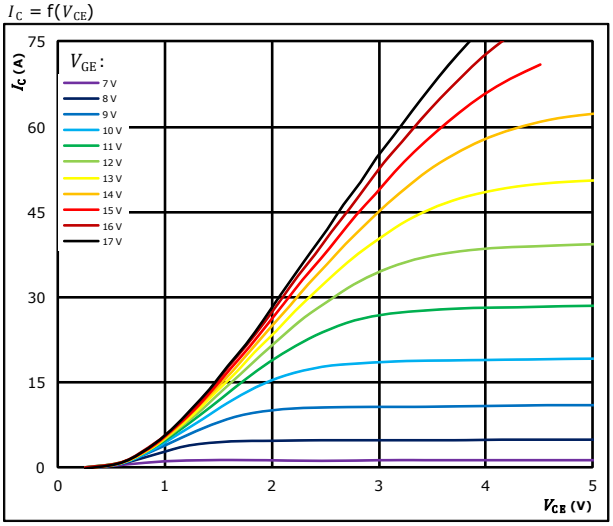


t_p =	250	µs		25 °C	
V_{GE} =	15	V	T_j:	125 °C	
				150 °C	

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

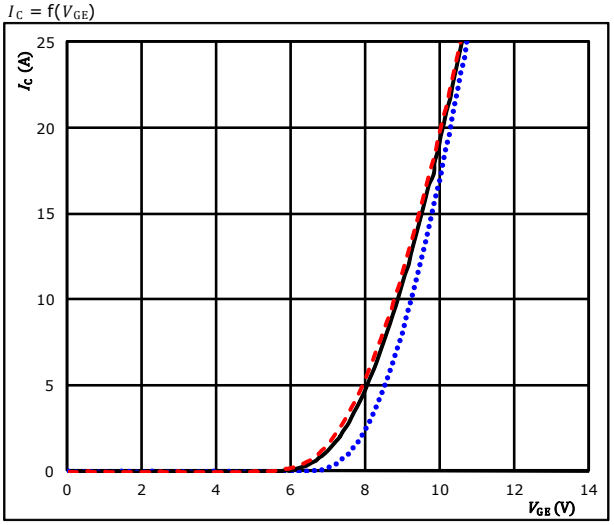


t_p =	250	µs
T_j =	125	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

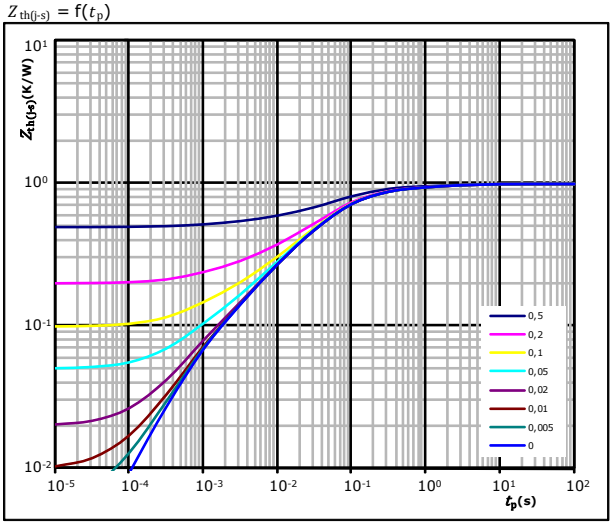


t_p =	100	µs		25 °C	
V_{CE} =	10	V	T_j:	125 °C	
				150 °C	

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	0,99	K/W

IGBT thermal model values

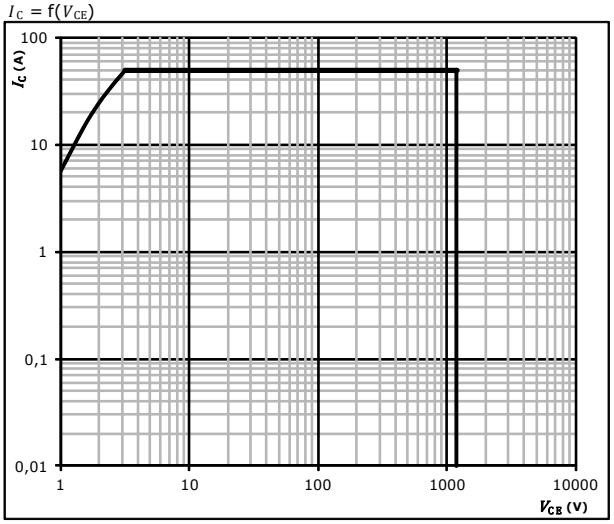
R (K/W)	τ (s)
4,63E-02	3,30E+00
9,24E-02	6,11E-01
3,21E-01	1,10E-01
3,46E-01	3,54E-02
1,30E-01	6,40E-03
5,27E-02	8,33E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



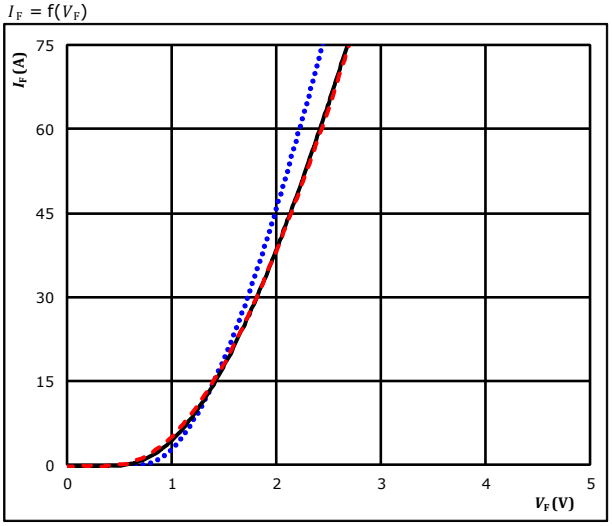
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



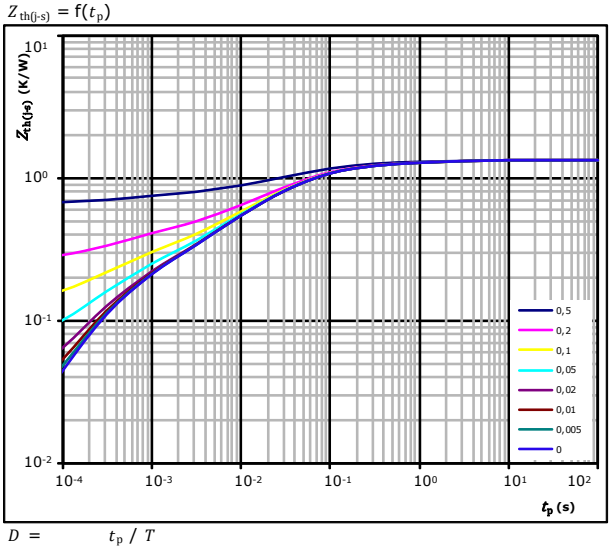
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 1,34 K/W

FWD thermal model values

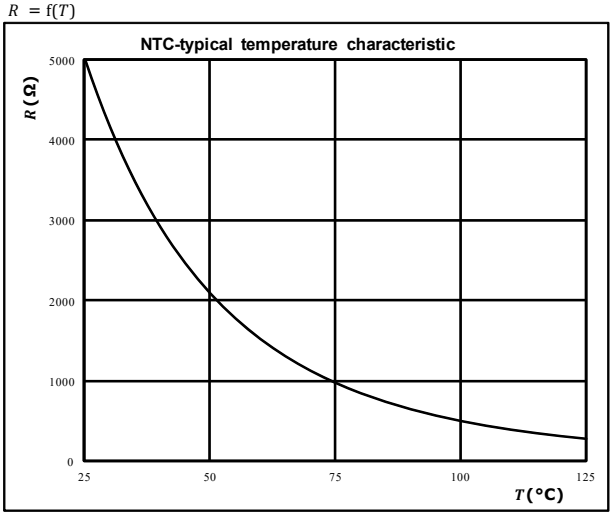
R (K/W)	τ (s)
7,90E-02	2,29E+00
1,38E-01	2,89E-01
5,15E-01	5,53E-02
3,34E-01	1,22E-02
1,30E-01	2,48E-03
1,40E-01	3,42E-04

Thermistor Characteristics

figure 1. **Thermistor**

Typical NTC characteristic as a function of temperature

$R = f(T)$

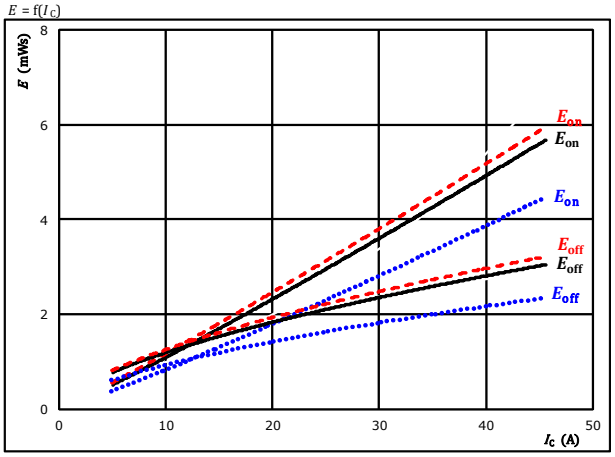


Inverter Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



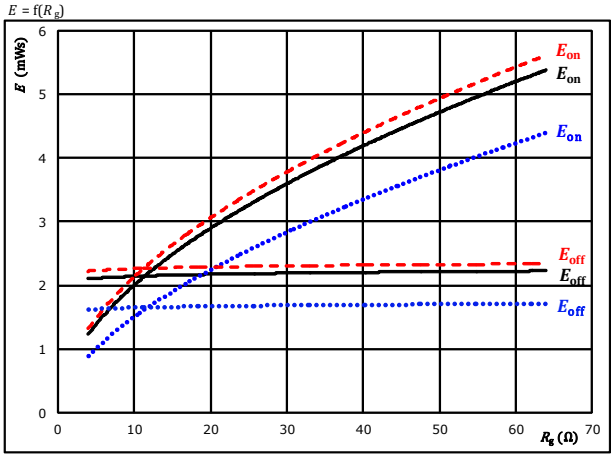
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
R_{gon} =	16	Ω		150 °C	
R_{goff} =	16	Ω			

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



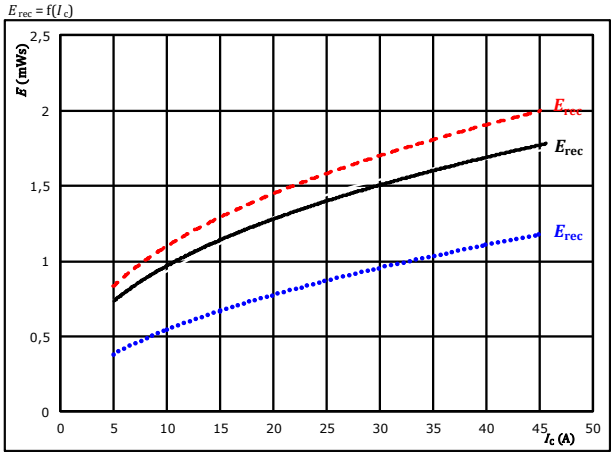
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
I_C =	25	A		150 °C	

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



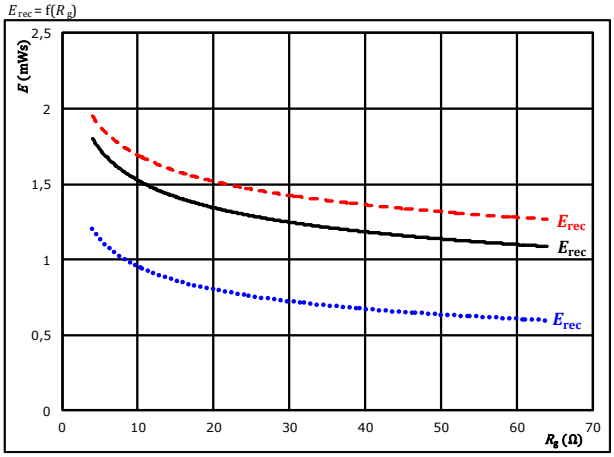
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
R_{gon} =	16	Ω		150 °C	

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

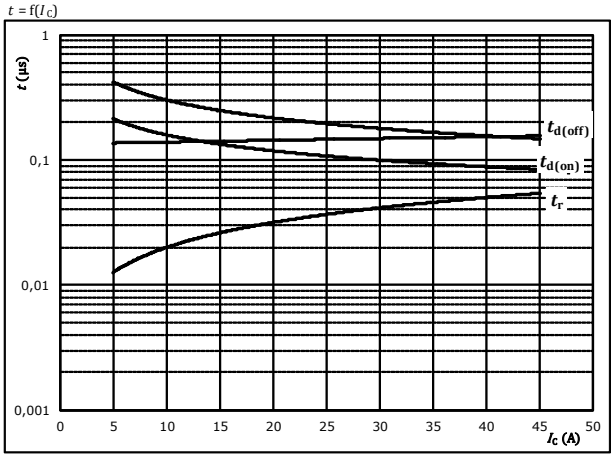
V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
I_C =	25	A		150 °C	

Inverter Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



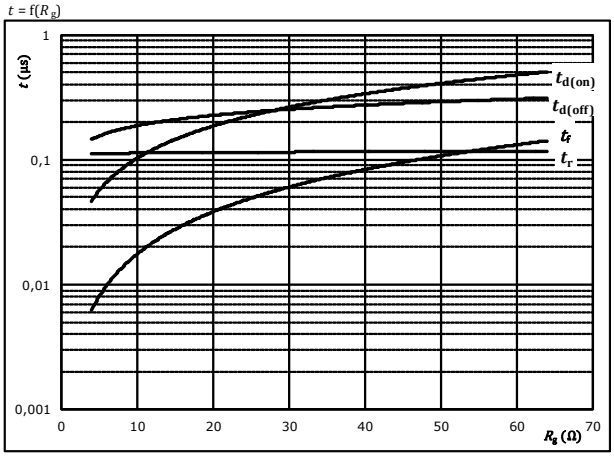
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	16	Ω
R_{goff} =	16	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



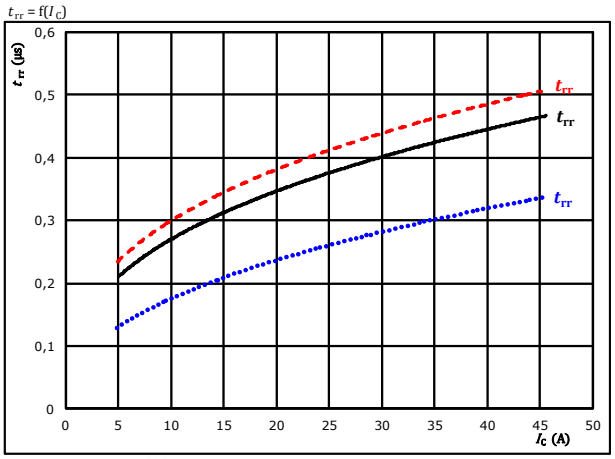
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	25	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

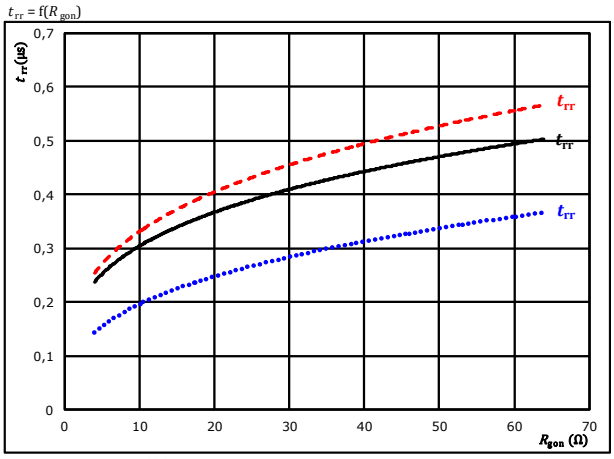


At					
V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
R_{gon} =	16	Ω		150 °C	

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



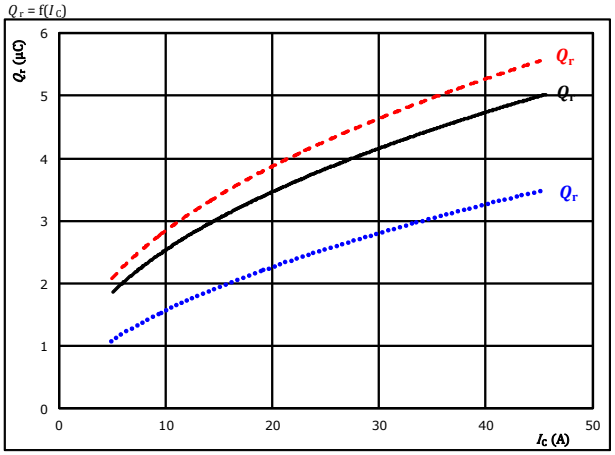
At					
V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
I_C =	25	A		150 °C	

Inverter Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

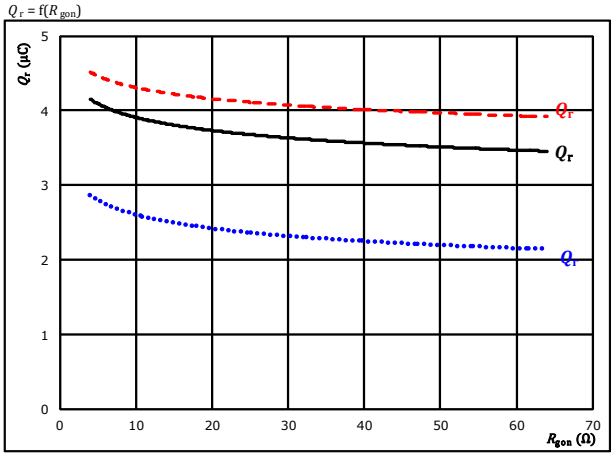


At					
V_{CE} =	600	V		25 °C	
V_{GE} =	±15	V	T_j:	125 °C	
R_{gon} =	16	Ω		150 °C	

figure 10. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

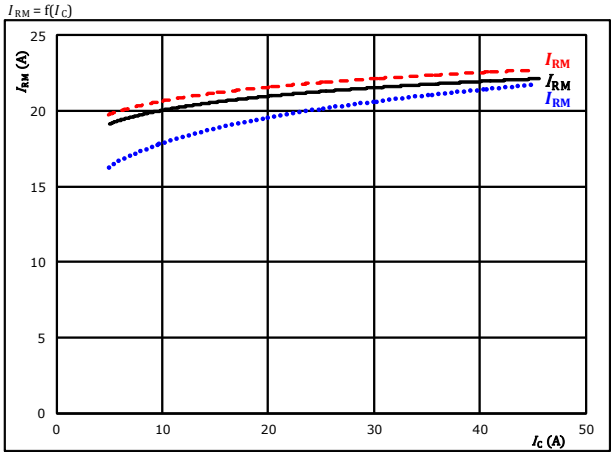


At					
V_{CE}=	600	V		25 °C	
V_{GE} =	±15	V	T_j:	125 °C	
I_C=	25	A		150 °C	

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

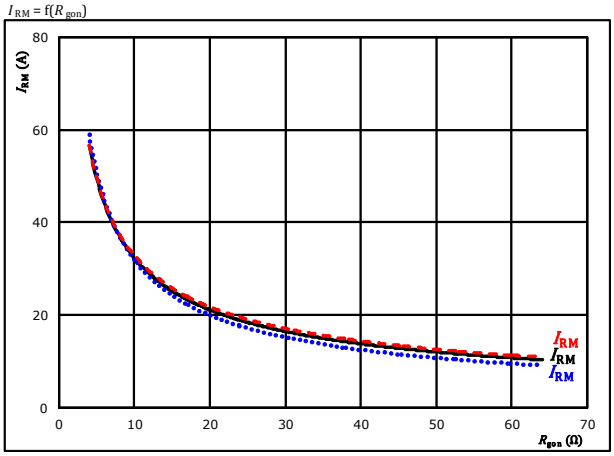


At					
V_{CE} =	600	V		25 °C	
V_{GE} =	±15	V	T_j:	125 °C	
R_{gon} =	16	Ω		150 °C	

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



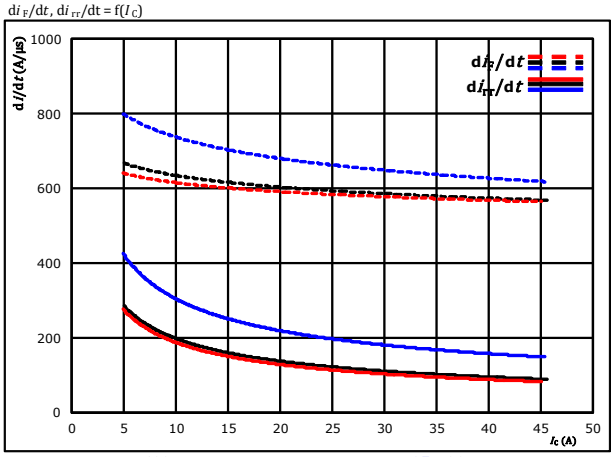
At					
V_{CE} =	600	V		25 °C	
V_{GE} =	±15	V	T_j:	125 °C	
I_C =	25	A		150 °C	

Inverter Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, $di_{rr}/dt = f(I_C)$

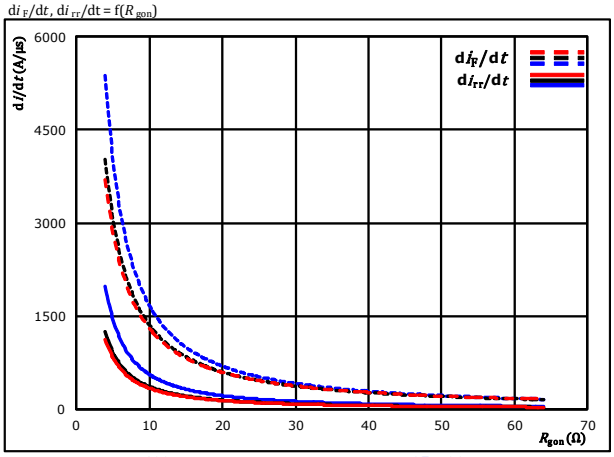


At						
V_{CE} =	600	V		25	°C
V_{GE} =	±15	V	T_j:	125	°C
R_{gon} =	16	Ω		150	°C

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

di_F/dt, $di_{rr}/dt = f(R_{gon})$

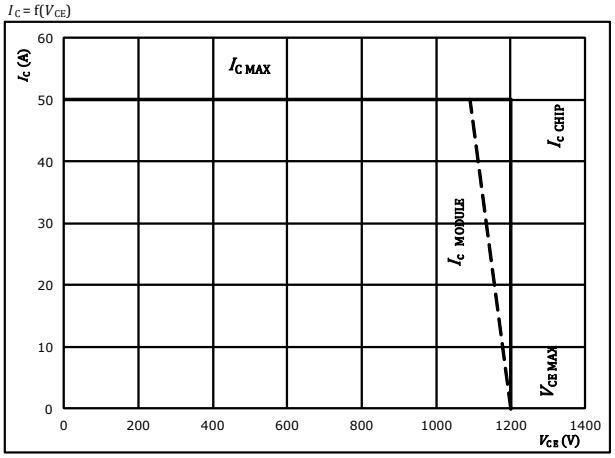


At						
V_{CE} =	600	V		25	°C
V_{GE} =	±15	V	T_j:	125	°C
I_C =	25	A		150	°C

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j =	125	°C
R_{gon} =	16	Ω
R_{goff} =	16	Ω

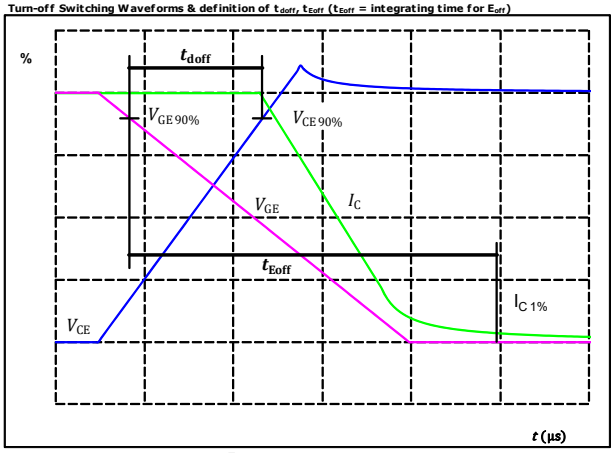
Inverter Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	16 Ω
R_{goff}	=	16 Ω

figure 1. IGBT

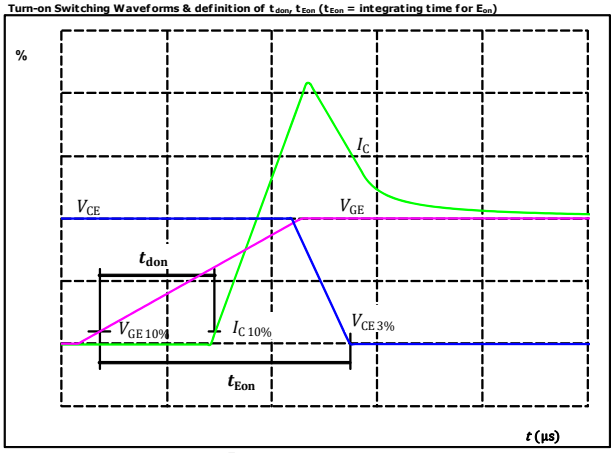
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	25	A
t_{doff} =	191	ns

figure 2. IGBT

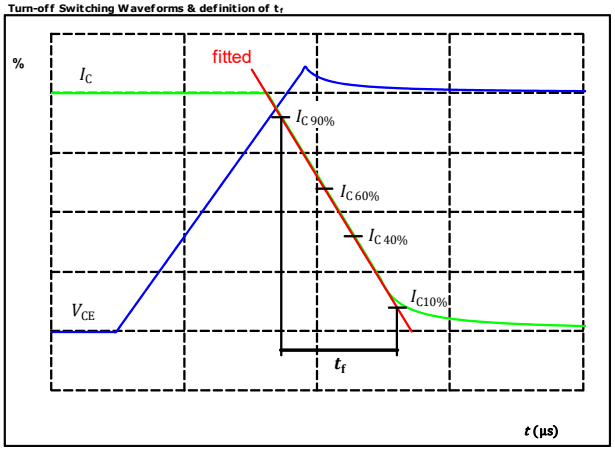
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	25	A
t_{don} =	149	ns

figure 3. IGBT

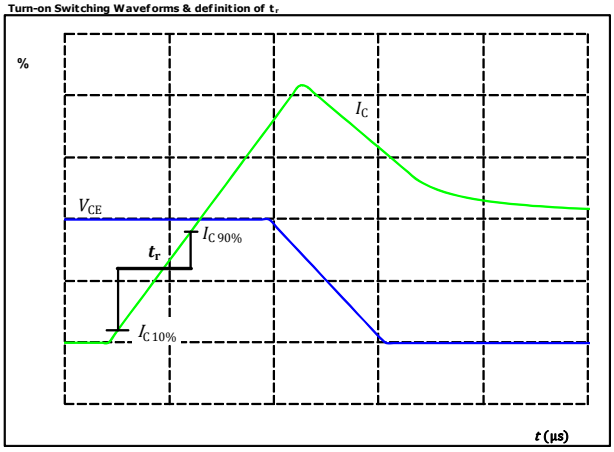
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	25	A
t_f =	110	ns

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

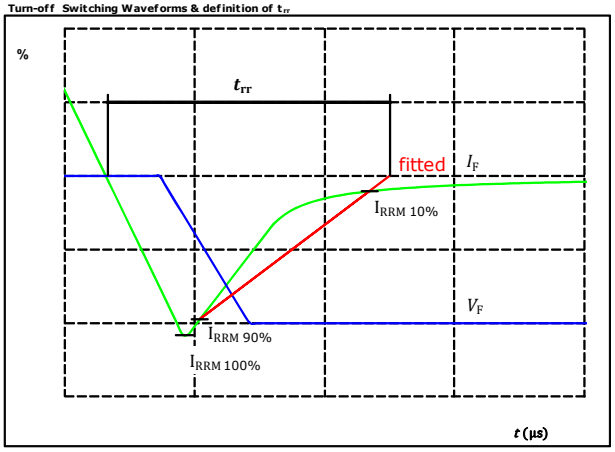


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	25	A
t_r =	33	ns

Inverter Switching Characteristics

figure 5. **FWD**

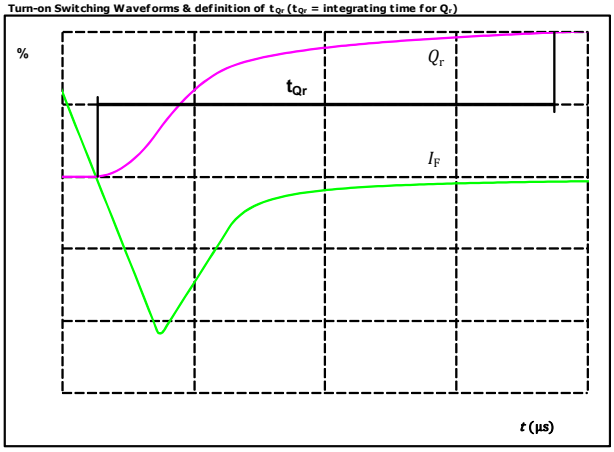
Turn-off Switching Waveforms & definition of t_{rr}



V_F (100%) =	600	V
I_F (100%) =	25	A
I_{RRM} (100%) =	23	A
t_{rr} =	367	ns

figure 6. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



I_F (100%) =	25	A
Q_r (100%) =	3,88	µC

Ordering Code & Marking

Version	Ordering Code
without thermal paste 12 mm housing with Press-fit pins	10-EZ126PA025M7-L858F78T
without thermal paste 12 mm housing with solder pins	10-E1126PA025M7-L858F78Z
with thermal paste 12 mm housing with Press-fit pins	10-EZ126PA025M7-L858F78T-/3/
with thermal paste 12 mm housing with solder pins	10-E1126PA025M7-L858F78Z-/3/

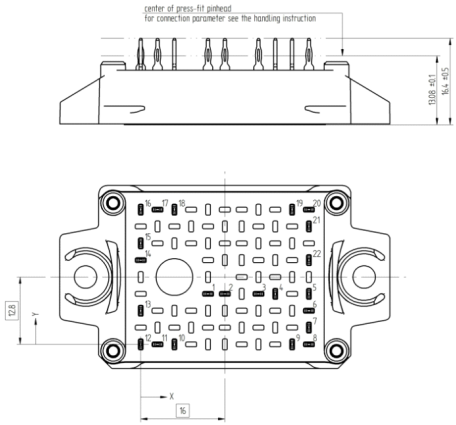
Text	**Name**		**Date code**	**UL & VIN**	**Lot**	**Serial**
	NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
Datamatrix	**Type&Ver**	**Lot number**	**Serial**	**Date code**		
	TTTTTTTVV	LLLLL	SSSS	WWYY		

Outline

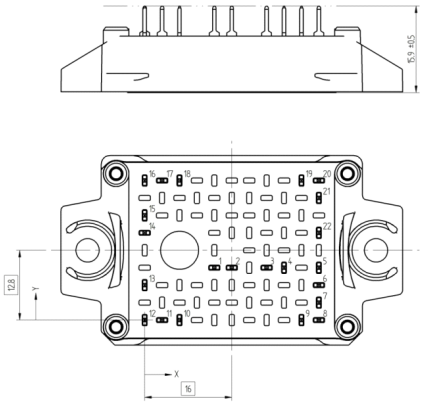
Pin table

Pin	X	Y	Function
1	12,8	9,6	DC+
2	16	9,6	DC+
3	22,4	9,6	Therm1
4	25,6	9,6	Therm2
5	32	9,6	DC-2
6	32	6,4	S13
7	32	3,2	DC-1
8	32	0	S11
9	28,8	0	G11
10	6,4	0	Ph1
11	3,2	0	Ph1
12	0	0	G12
13	0	6,4	G14
14	0	16	Ph2
15	0	19,2	Ph2
16	0	25,6	G16
17	3,2	25,6	Ph3
18	6,4	25,6	Ph3
19	28,8	25,6	G15
20	32	25,6	S15
21	32	22,4	DC-3
22	32	16	G13

L858F78T

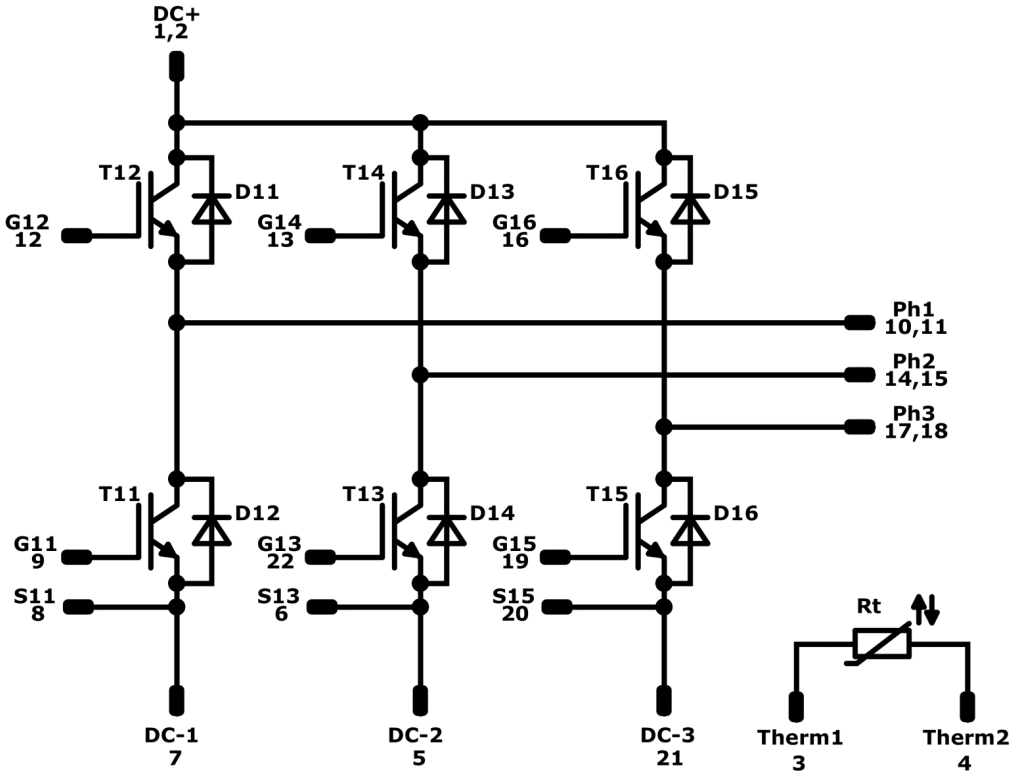


L858F78Z



Tolerance of pinpositions ±0,4mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	25 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	1200 V	25 A	Inverter Diode	
Rt	NTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* E1 packages see vincotech.com website.

Package data
Package data for *flow* E1 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-Ex126PA025M7-L858F78x-D2-14	04 Sep. 2018	Solder pin version added	1, 2, 14

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.